

Technical Data Sheet

EVSF100LFG is a tough, wear-resistant, tensile-strength, thermally conductive silicone pad that is used to fill two pressure-sensitive or vibrating interfaces to allow air to escape from the interface and improve thermal conductivity. The product is self-adhesive and can be die cut into various shapes for easy assembly. Thermal conductivity is 1.0W/MK.



Material Properties

- Semiconductor heat sink
- Vehicle navigator
- Communication & power equipment
- Graphics card, memory module
- LED lighting equipment
- LCD and plasma TV



EVSF100-LFG

Color	White	Visual
Thickness	0.3 ~ 10.0mm	ASTM D374
Specific Gravity	2.2g/cc	ASTM D792
Thermal Conductivity	1.0 W/m-K	ASTM D5470
Hardness (Shore OO)	50~75。	ASTM D2240
Elongation	4%	ASTM D412
Tensile Strength	130psi	ASTM D412
Electrical Strength	>200VAC/mil	ASTM D149
UL Flammability Rating	UL94 V-0	
Volume resistivity	7*10 ¹³ Ω.cm	ASTM D257
Operating Temperature	-50 ~ 200°C	---
Thermal Resistance(1mm,@40psi)	1.0°C*in ² /W	ASTM D5470
Compression Ratio(1mm,@40psi)	20%	---
Dielectric Constant MHz	NA	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

CR Technology, Inc

📍 55 Chase St. Methuen,
Massachusetts 01844

✉ sales@crtechinc.com

☎ 978.681.5300

Note: The information provided herein is accurate at time of publication. It is the responsibility of the end-user to confirm compliance to their application. All test data is typical. Therefore, these recommendations and data are for reference only and not as a product warranty.